

a conductive trace connecting each of the metallized pads to a corresponding bond pad on the surface of the semiconductor wafer.

4. The chip scale structure of Claim 15 further comprising a solder ball formed on each metallized pad on the glass sheet.

Please cancel Claim 16.

17. A chip scale structure comprising:

a semiconductor wafer with a pattern of bond pads on a surface of the semiconductor wafer, wherein the bond pads can be formed anywhere on the surface of the semiconductor wafer;

a glass sheet with holes in a pattern matching the pattern of bond pads on the surface of the semiconductor wafer;

a layer of adhesive adhering the glass sheet to the semiconductor wafer, wherein the holes in the glass sheet are over the bond pads on the surface of the semiconductor wafer; and

metallized pads formed on the glass sheet adjacent to each hole in the glass sheet, wherein the metallized pad extends down a portion of a side of the hole in the glass sheet.

6. The chip scale structure of Claim 17 further comprising a metal plug formed in each hole connecting the metallized pad extending down a portion of a side of the hole in the glass sheet to the bond pad under the hole in the glass sheet.

7. The chip scale structure of Claim 6 further comprising a solder ball formed on each metallized pad on the glass sheet.

#### REMARKS

Claims 4, 6, 7, 15, 16 and 17 are pending in the application. Applicant has canceled Claim 16. Claims 4, 6, 7, 15 and 17 remain in the application. Applicant submits that the Claims, as amended, overcome the rejection by the Examiner and all of the objections of the Examiner and request an early allowance.